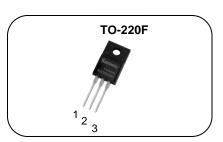


N-channel Enhanced mode TO-220F MOSFET

Features

- High ruggedness
- Low R_{DS(ON)} (Typ 0.15Ω)@V_{GS}=10V
 Low Gate Charge (Typ 60nC)
- Improved dv/dt Capability
- 100% Avalanche Tested
- Application:LED,Charge,PC Power



1. Gate 2. Drain 3. Source

$BV_{DSS}:600V$: 20A I_D $R_{DS(ON)}: 0.15\Omega$





General Description

This power MOSFET is produced with super junction advanced technology of SAMWIN. This technology enable the power MOSFET to have better characteristics, including fast switching time, low on resistance, low gate charge and especially excellent avalanche characteristics.

Order Codes

Item	Sales Type	Marking	Package	Packaging
1	SW F 20N60K	SW20N60K	TO-220F	TUBE

Absolute maximum ratings

Symbol	Parameter		Value	Unit
V _{DSS}	Drain to source voltage	source voltage		V
	Continuous drain current (@T _C =25°C)		20*	А
I _D	Continuous drain current (@T _C =100°C)		12.6*	А
I _{DM}	Drain current pulsed	(note 1)	80	А
V_{GS}	Gate to source voltage		±30	V
E_AS	Single pulsed avalanche energy	(note 2)	500	mJ
E_AR	Repetitive avalanche energy	(note 1)	20	mJ
dv/dt	MOSFET dv/dt ruggedness (@VDS=0~400V)		30	V/ns
dv/dt	Peak diode recovery dv/dt	(note 3)	20	V/ns
Ъ	Total power dissipation (@T _C =25°C)		35.9	W
P_{D}	Derating factor above 25°C		0.3	W/ºC
T_{STG},T_{J}	Operating junction temperature & storage temperature Maximum lead temperature for soldering purpose, 1/8 from case for 5 seconds.		-55 ~ + 150	°C
T _L			300	°C

^{*.} Drain current is limited by junction temperature.

Thermal characteristics

Symbol	Parameter	Value	Unit
R _{thjc}	Thermal resistance, Junction to case	3.48	°C/W
R _{thja}	Thermal resistance, Junction to ambient	47.3	°C/W



Electrical characteristic ($T_C = 25$ °C unless otherwise specified)

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
Off charac	teristics			•		
BV _{DSS}	Drain to source breakdown voltage	V _{GS} =0V, I _D =250uA	600			V
ΔBV _{DSS} / ΔT _J	Breakdown voltage temperature coefficient	I _D =250uA, referenced to 25°C		0.64		V/ºC
		V _{DS} =600V, V _{GS} =0V			1	uA
I _{DSS}	Drain to source leakage current	V _{DS} =480V, T _C =125°C			50	uA
	Gate to source leakage current, forward	V _{GS} =30V, V _{DS} =0V	(5	2)	100	nA
I _{GSS}	Gate to source leakage current, reverse	V _{GS} =-30V, V _{DS} =0V	_		-100	nA
On charac	teristics	0.4				
$V_{GS(TH)}$	Gate threshold voltage	$V_{DS}=V_{GS}$, $I_{D}=250uA$	2		5	V
R _{DS(ON)}	Drain to source on state resistance	V _{GS} =10V, I _D =10A		0.15	0.18	Ω
G_fs	Forward transconductance	V _{DS} =30V, I _D =10A		14		S
Dynamic c	haracteristics		1		•	
C _{iss}	Input capacitance		199	2100		pF
C _{oss}	Output capacitance	V _{GS} =0V, V _{DS} =200V, f=1MHz	1	79		
C _{rss}	Reverse transfer capacitance		James .	3.1		
t _{d(on)}	Turn on delay time			28		
t _r	Rising time	V_{DS} =300V, I_{D} =20A, R_{G} =25 Ω		52		ns
t _{d(off)}	Turn off delay time	V _{GS} =0V (note 4,5)		116		
t _f	Fall time			40		
Q_g	Total gate charge			60		nC
Q_{gs}	Gate-source charge	V_{DS} =520V, V_{GS} =10V, I_{D} =20A (note 4,5)		17		
Q_{gd}	Gate-drain charge	(1.5.5 1,5)		26		

Source to drain diode ratings characteristics

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
I _s	Continuous source current	Integral reverse p-n Junction diode in the MOSFET			20	Α
I _{SM}	Pulsed source current				80	Α
V _{SD}	Diode forward voltage drop.	I _S =20A, V _{GS} =0V			1.4	V
t _{rr}	Reverse recovery time	I _S =20A, V _{GS} =0V,		366		ns
Q _{rr}	Reverse recovery charge	dl _F /dt=100A/us		6.8		uC

X. Notes

- Repeatitive rating : pulse width limited by junction temperature. 1.
- L = 62.5mH, I_{AS} = 4A, V_{DD} =50V, R_{G} =25 Ω , Starting T_{J} = 25°C I_{SD} ≤ 20A, di/dt = 100A/us, V_{DD} ≤ BV_{DSS}, Staring T_{J} =25°C Pulse Test : Pulse Width ≤ 300us, duty cycle ≤ 2%. 2.
- 3.
- 4.
- Essentially independent of operating temperature.

Fig. 1. On-state characteristics

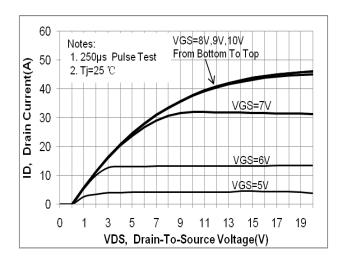


Fig. 3. Gate charge characteristics

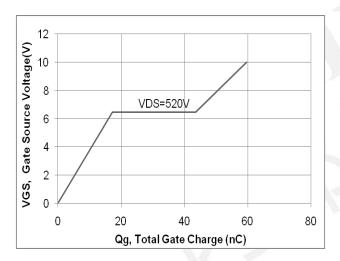


Fig 5. Breakdown Voltage Variation vs. Junction Temperature

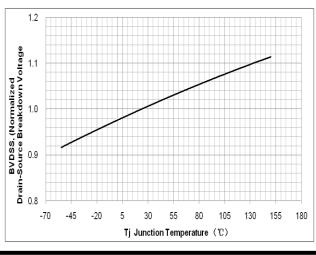


Fig. 2. On-resistance variation vs. drain current and gate voltage

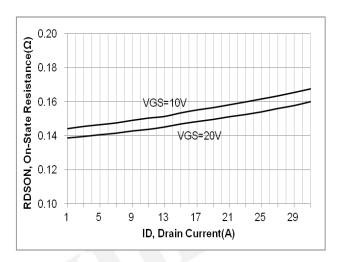


Fig. 4. On state current vs. diode forward voltage

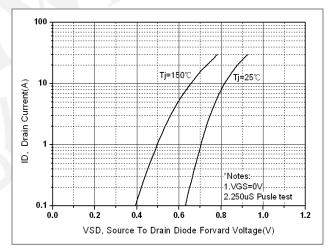


Fig. 6. On resistance variation vs. junction temperature

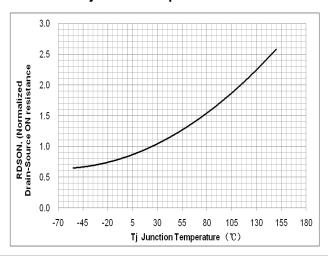


Fig. 7. Maximum safe operating area

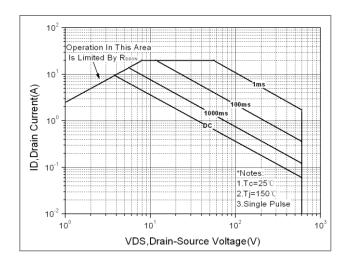


Fig. 8. Capacitance Characteristics

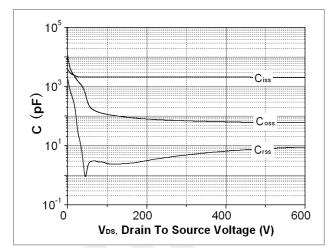


Fig. 9. Transient thermal response curve

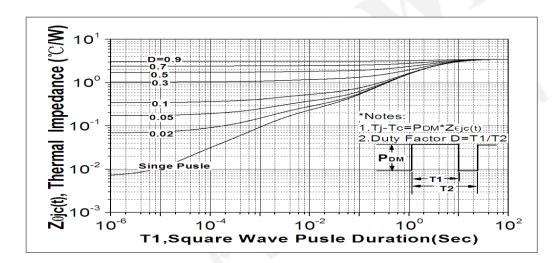


Fig. 10. Gate charge test circuit & waveform

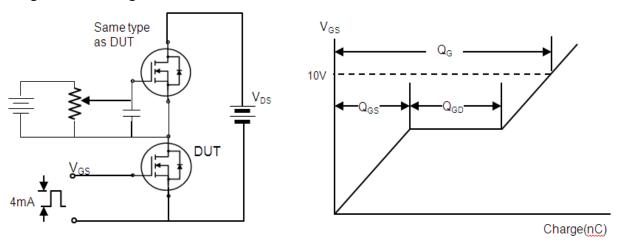


Fig. 11. Switching time test circuit & waveform

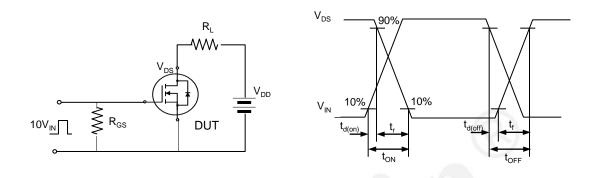


Fig. 12. Unclamped Inductive switching test circuit & waveform

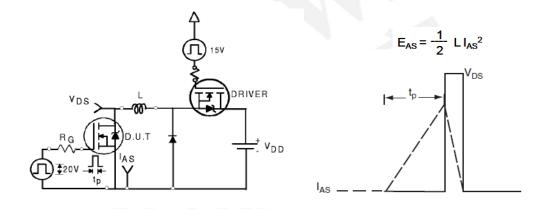
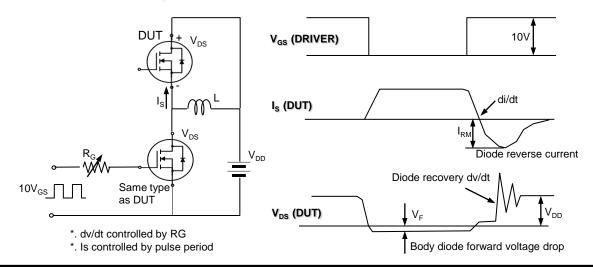


Fig. 13. Peak diode recovery dv/dt test circuit & waveform







DISCLAIMER

- * All the data & curve in this document was tested in XI' AN SEMIPOWER TESTING & APPLICATION CENTE R.
- * This product has passed the PCT,TC,HTRB,HTGB,HAST,PC and Solderdunk reliability tes .
- * Qualification standards can also be found on the Web site (http://www.semipower.com.cn)
- * Suggestions for improvement are appreciated, Please send your suggestions to samwin@samwinsemi.com

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